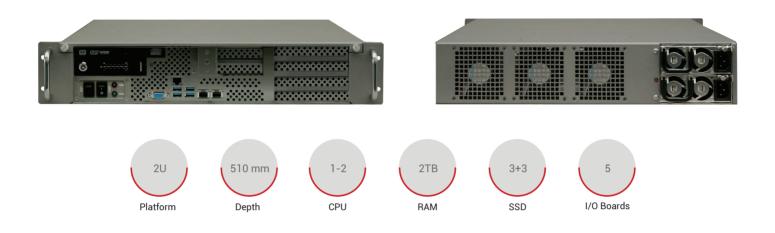
GAP-251F - G5 Series 2U RUGGED SERVER



Intel[®] Xeon[®] Broadwell-EP Front I/O - Rear Power Supply



GAP is a line of rugged servers and workstations with aluminum construction, designed for applications that require a robust and qualified MIL-GRADE device, suitable for operating in critical environments.

GAP-251F G5 series series rugged server features single or dual socket Intel[®] Xeon[®] E5 v4 (Broadwell-EP) supporting up to 22 cores (44 threads with Hyper-Threading Technology), up to 55 MB of L3 cache per CPU, 2400MHz DDR4 up to 2TB and 40 PCIe lanes. The integrated IPMI services support monitoring, control, and management functions and provides for alarm notifications in case of critical events.

GAP-251F is designed for 19" rackmounting and has a 2U chassis with 510mm depth.

The front I/O and rear power supply layout includes three removable SSD, three internal SSD and an optional slim DVD. GAP-251F rugged servers can host up to two low profile PCIe cards and two standard PCIe cards and one dual slot PCIe card.

The additional boards are equipped with dedicated fixing systems to ensure optimal operation even in the presence of shock and vibration or during transport.

GAP servers are qualified according to MIL-STD-810G for temperature, shock and vibration and can optionally conform to MIL-STD-461 for EMI /EMC. Upon request, the integrated devices, complete with I / O cards, can be subjected to specific profiles of thermal or mechanical stress. Versions with MIL grade connectors on I/O ports and power input are available.

All units are delivered with their inventory list to ensure configuration control and reproducibility over time.

FEATURES

- 2U Rugged Server 510mm depth
- Single or Dual Processor
- E5 Series Intel[®] Xeon[®] processors Broadwell-EP
- Front I/O connectors
- Rear Power Input
- Redundant AC or DC Power Supply
- Up to 3 removable 2.5" SSD + 3 x internal 2.5" SSD
- Optional DVD
- Up to 5 PCIe boards
- Optional Conformal Coating
- MIL-STD-810G
- Optional MIL-STD-461



Technical Specifications

Processor Intel [®] Xoon [®] ES-2600 V4/X (up to 1480 TDP) dual socket R3 (LGA 2011) - Up to 22 cores Memory Up to TTB 3DS ECC HDIMM, DDM-2400MH2 Chipet Intel [®] 617 Network 2 K 2456 Gigabit Etheres Storage 2 K 2456 Gigabit Etheres Method 1 FM Heade Mothodard I/O Value on the frant: 1 x VGA, 4 x USB 30, 2 x GEc, 1 x IPM Apparison slots 2 X PCIe - Bracket FUI Height Strenge Systems Value System Site Site Site Site Site Site Site Site	System	
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	Transport shock	MIL-STD-810G Proc. II Method 516.7 - 30g / 9ms sawtooth
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GAP servers and workstations are designed in accordance with the environmental specifications indicated. Some parameters depend on the configuration. Equipment may be subjected to dedicated test profiles.